

WE LOOK AFTER THE EARTH BEAT



HIVAC - VASP1 ASIC

Contract 4200019872

Final presentation

Sept 2014

Xavier Lhuillier – TAS Toulouse

03/09/2014

Ref.:0005-0005600133

THALES ALENIA SPACE



- Introduction on HIVAC contract
 - HIVAC Activity
 - VASP0 ASIC development
- VASP1 ASIC development
 - Specification
 - Design
 - Manufacturing
 - Electrical test
 - Radiation test
- VASP1 datasheet
- VASP1 application
- FM production
- Conclusion

Introduction on HIVAC contract

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VASP1 ASIC development

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VASP1 datasheet

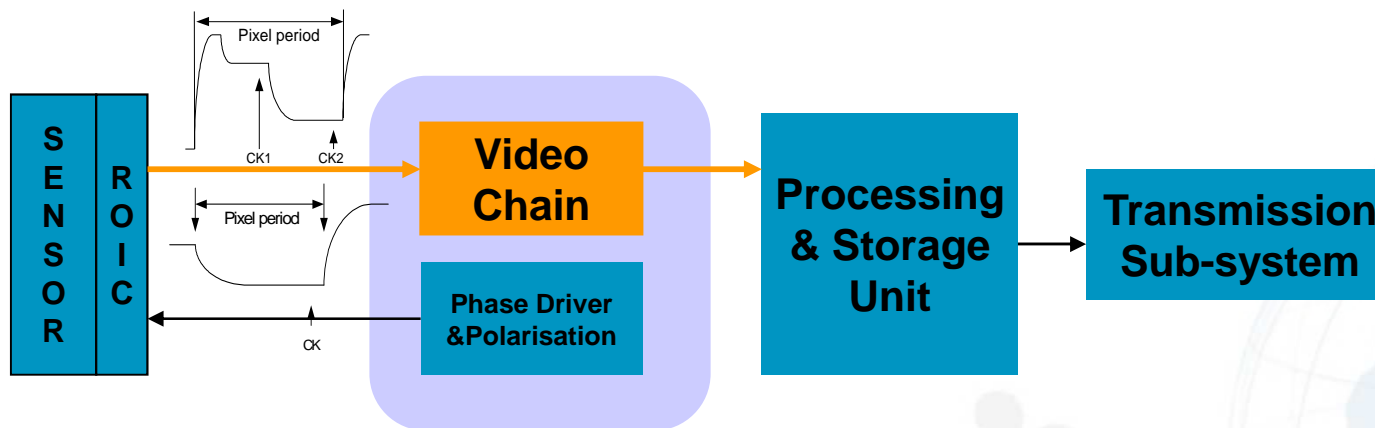
VASP1 application

FM production

Conclusion

Project Context

- Optical satellite instruments, Earth observation and avionics units :⁴
 - use widely Charge Coupled Devices and CMOS Active Pixel Sensors
 - Need a specific conditioning of the analog signals from the read-out circuits before processing and storage, including :
 - Amplification and filtering
 - Analog to digital conversion
 - Challenging constraints
 - Performance : Noise reduction, sensitivity maximisation, power dissipation
 - Environment : temperature range, radiation, lifetime
 - Increase the integration level



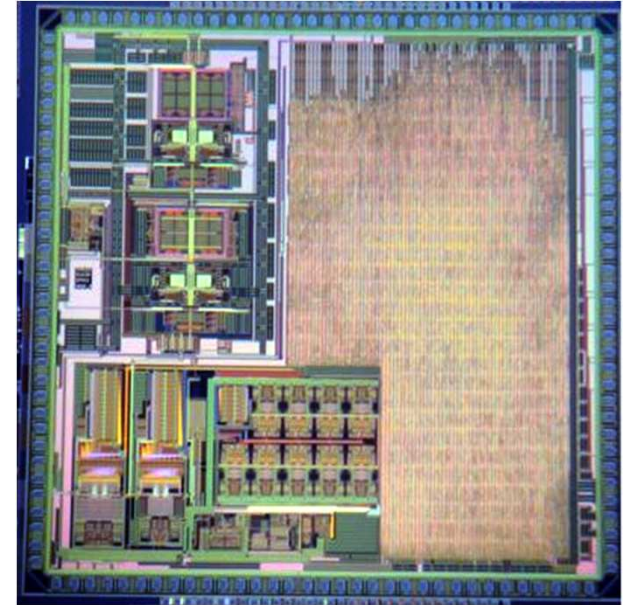
ESA has initiated the HIVAC activity (07/2006)

- Highly Integrated Video Acquisition Chain
- Contract n° 4200019872
- Thales Alenia Space granted as Prime contractor
- Design and validation of a video acquisition IC :
VASP = CDS + ADC

➤ **In the frame of HIVAC contract, VASP0 ASIC has been developed**

➤ **VASP0 Activities :**

- Detailed design Layout and simulations
- Foundry / prototypes manufacturing
- Test bench design and manufacturing for functional tests
- VASP functional tests on all prototypes
- Performance characterization
- Radiation tests (TID)



➤ **Sub-contractor withdrawn after ADC block design**

➤ **TAS-F finalized the VASP0 design up to top level**

VASPO specifications

Technology	0.35μm
Power Supply	3.3V
Power dissipation	350 mW
Analog functions	CDS or single sampling PGA 1 to 8 by step of 1 ADC
Pixel frequency	From 100 khz to 3 Mhz
Input signal type	CCD and CMOS compatibility
ADC resolution	16 bits
Noise	< 2 Lsb
ENOB	> 14 bits
DNL	< 1 Lsb
INL	< 3.5 Lsb
TID	50 krad
Latchup immunity	> 70 MeV.cm²/mg
Operational temperature range	-55$^{\circ}$C to 125$^{\circ}$C
Full performance temperature range	0$^{\circ}$C to 30$^{\circ}$C

- **100% functions validated from -30°C to +80°C**

- **Very good electrical performances**
 - Excellent noise
 - Observed degradation in some modes (reference stability issue)
 - Excellent linearity on the 16-bit ADC
 - Observed calibration overflow
 - Observed test bench limitations for accurate measurements
 - PGA not necessary: all the video chain is integrated

- **Radiation test**
 - Analog hardening working well
 - Digital not yet hardened

Special thanks for very good VASP0

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- **CHIPIDEA :** **Jorge GUILHERME (ADC designer)**

- **TAS-France :** **Didier CHEFDEVILLE (project leader)**
 Claude NEVEU (video chain expert)
 Philippe Ayzac (VASP0 responsible)
 Fabien TAUZIAC (VASP0 testing)

- **TAS-Italy :** **Edoardo TADDEI (VASP0 testing)**

- **ESA :** **Wahida GASTI (VASP0 technical officer in ESA)**

And the many other people !

➤ **Digital library hardening**

- Creation of ~50 hardened cells (schematic, layout)
- Verification of the design
- Characterization of timings and library generation

➤ **Analog design upgrade**

- Voltage reference improvement
- Completion of hardening (< 10% of analog part)

➤ **Foundry, packaging, tests**

➤ **Qualification in full compliance to ECSS-Q-ST-60**

- **Initiated by TAS during VASP upgrade design with ESA approval**
 - Remove the PGA
 - Review the calibration algorithm to remove the overflow
 - Increase of the ADC working frequency from 3 to 4 MHz
 - Integrate the low noise, high speed reference buffers
 - Integrate a clamp function
 - Integrate a pixel bus tri-state interface

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VASP1 ASIC development

– Specification

– Design

– Manufacturing

– Electrical test

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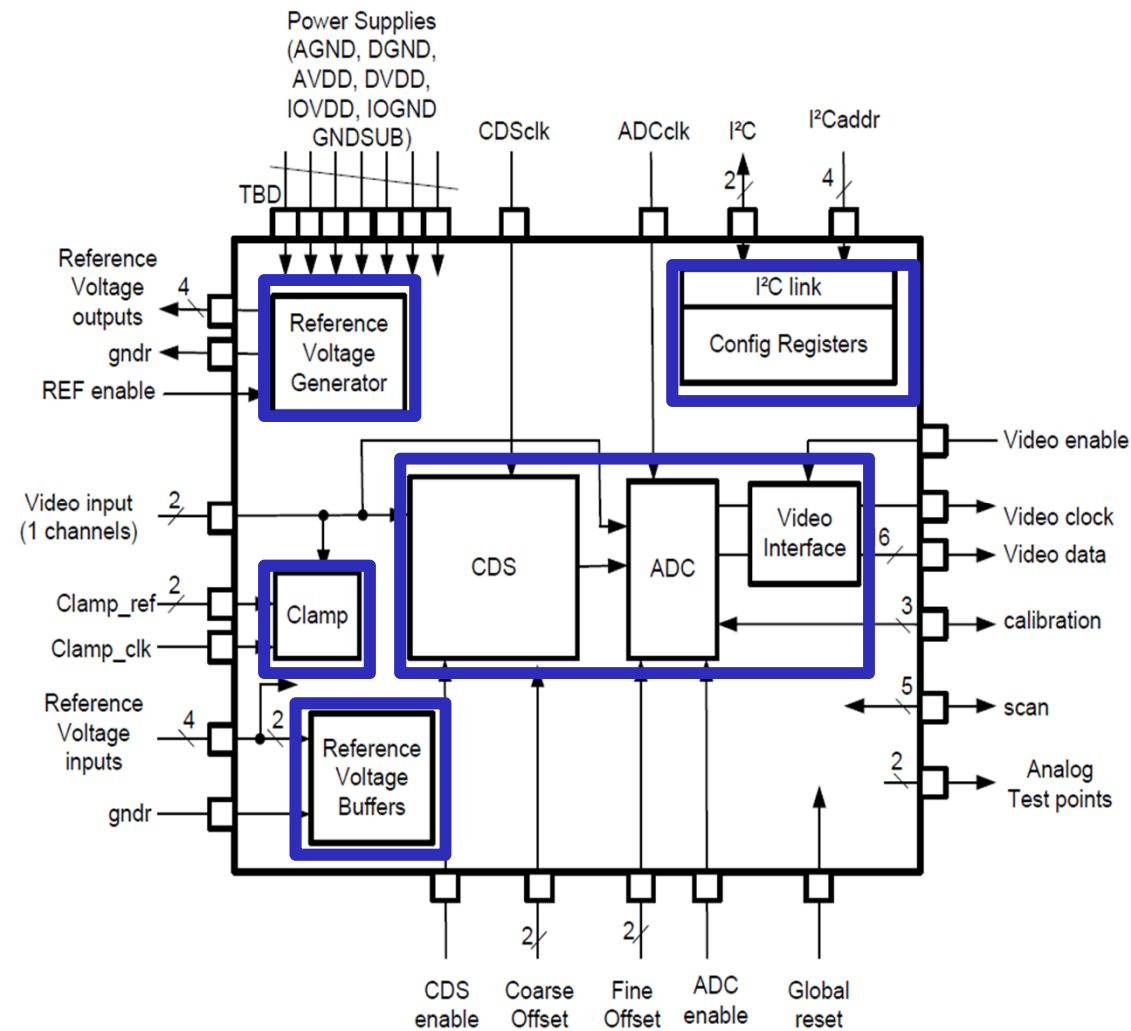
VASP1 datasheet

VASP1 application

FM production

Conclusion

- High performances CDS and 16-bit ADC, both running up to 4 MHz
- Multi-sampling per pixel capability
- Clamping circuit to manage detector DC voltage.
- Bandgap and VCM voltages generation. External references can also be used.
- Serial interface for configuration
- Internal reference buffering



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VASP1 datasheet

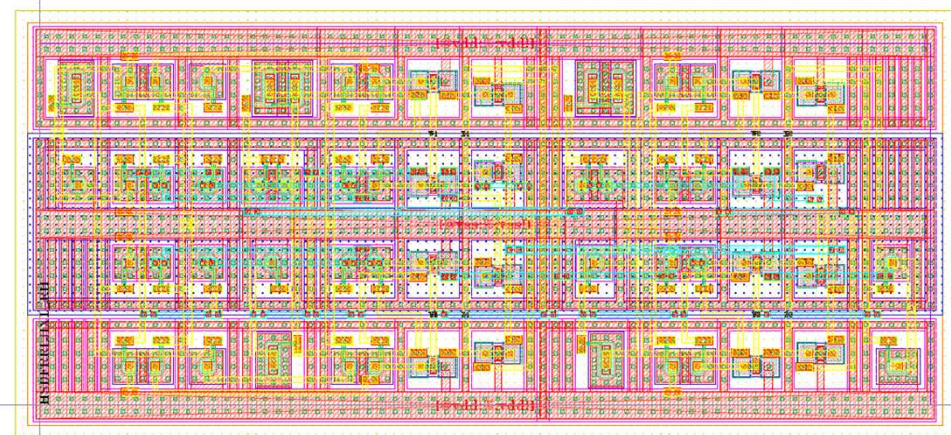
VASP1 application

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Conclusion

- Radiation hardening of digital library
- Voltage reference review
- Analog hardening completion
- PGA removal
- Calibration algorithm review
- Increase of the ADC working frequency from 3 to 4 MHz
- Integrate the low noise, high speed reference buffers
- Integrate a clamp function
- Integrate a pixel bus tri-state interface

- 56 logic cells, 14 layout cells, 5 digital I/Os
- **Radiation Hardening By Design**
 - TAS internal rules for schematic and layout
 - DICE register creation
 - Cell improvements to maintain the timing performances
- **Drive CAD company for complete characterization**
 - Functionality check
 - Arc timing extraction
 - Generation of digital tool format

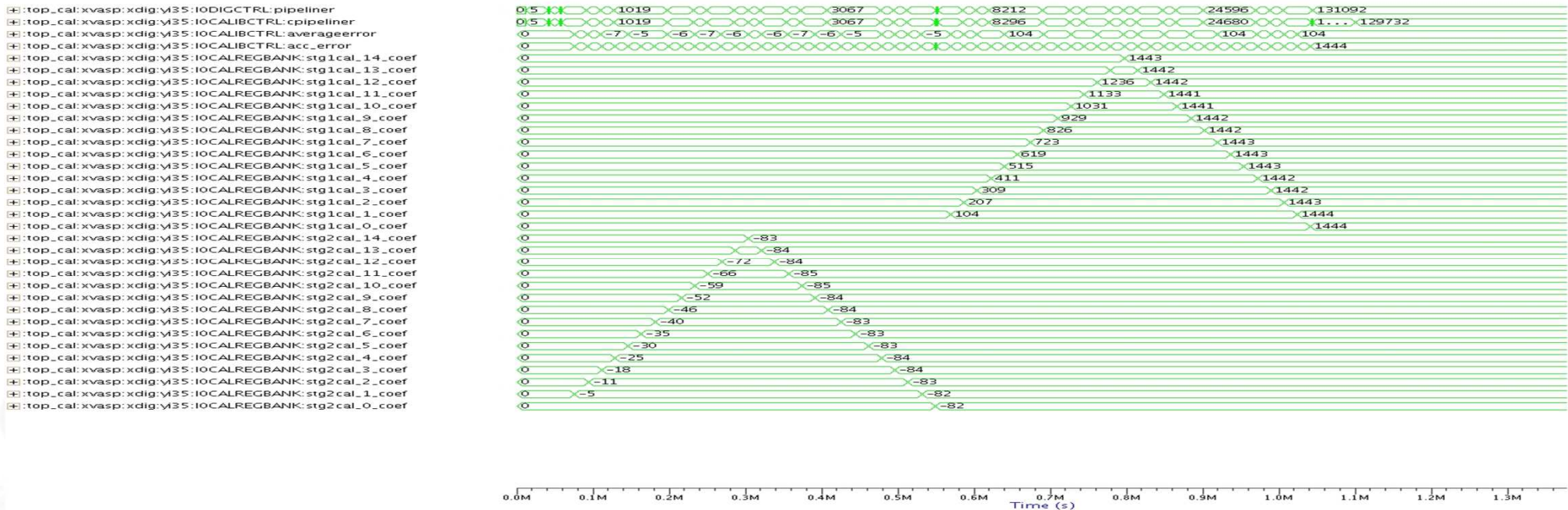


- **Review stability of the core circuit (banggap)**

- **Allow the use of external references**
 - Separate generator output pins from buffer input pins

- **Review the trim capability**
 - Band-gap temperature slope
 - Common mode absolute value
 - VREF absolute value

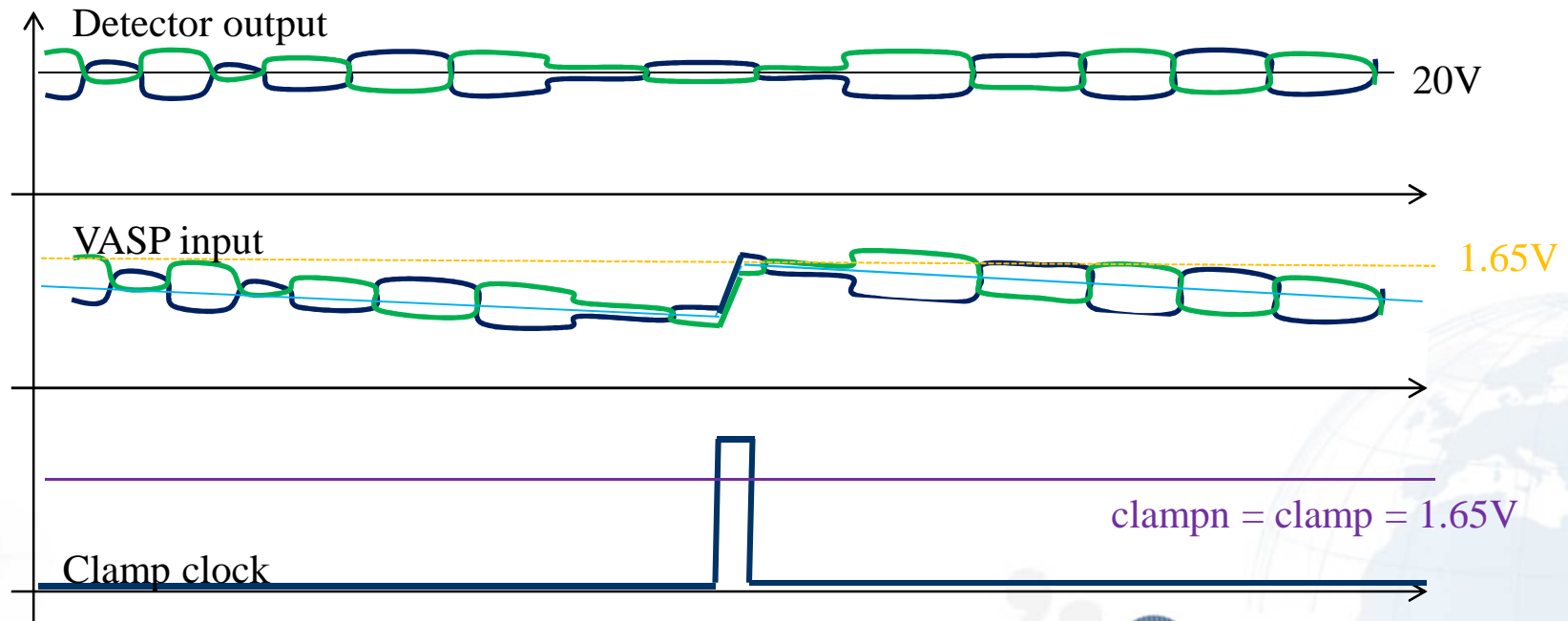
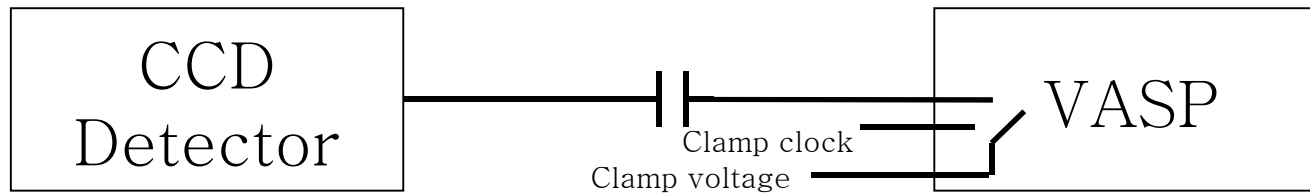
- Find an improvement in the algorithm
 - Need to take into account ADC amplifier offset
 - Improved algorithm, derived from the existing one
 - Improved algorithm simulated in mixed-mode simulation



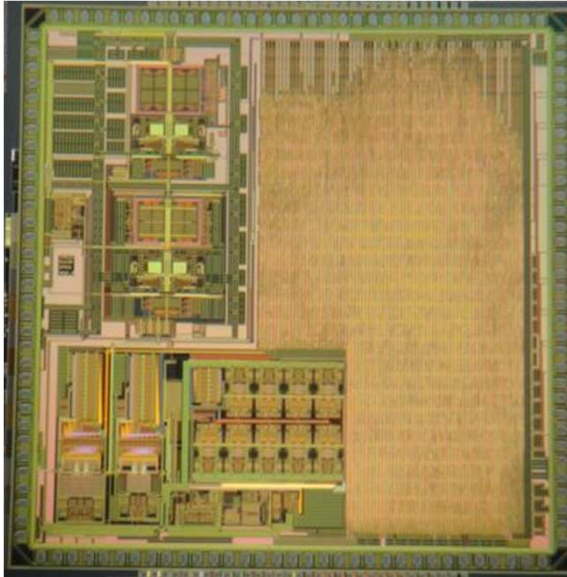
- **Reference need to be buffered for CDS, ADC use**
- **Specifications**
 - Low consumption
 - Low noise
 - High gain and bandwidth
 - Large input and output dynamic range
- **Those differential buffers have been integrated**
- **Offset correction inputs (COC and FOC) have also been buffered**

Clamp function

- The clamp is used with CDD detector to bias the decoupling capacitor that is needed to go from detector high voltage to VASP low voltage.



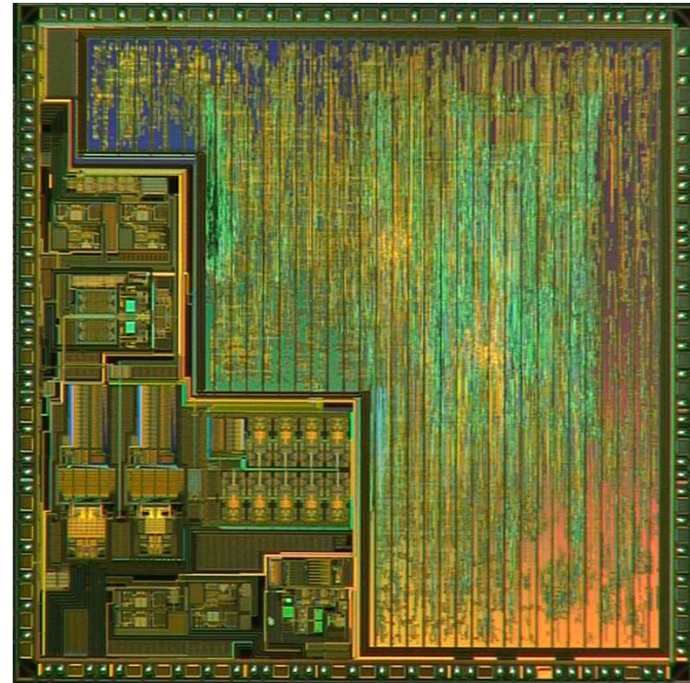
VASP evolution



VASPO - 39mm² - 132 IOs

Hardening : Analog 90% - Digital 0%

ADC only consumption : 35 mA typ

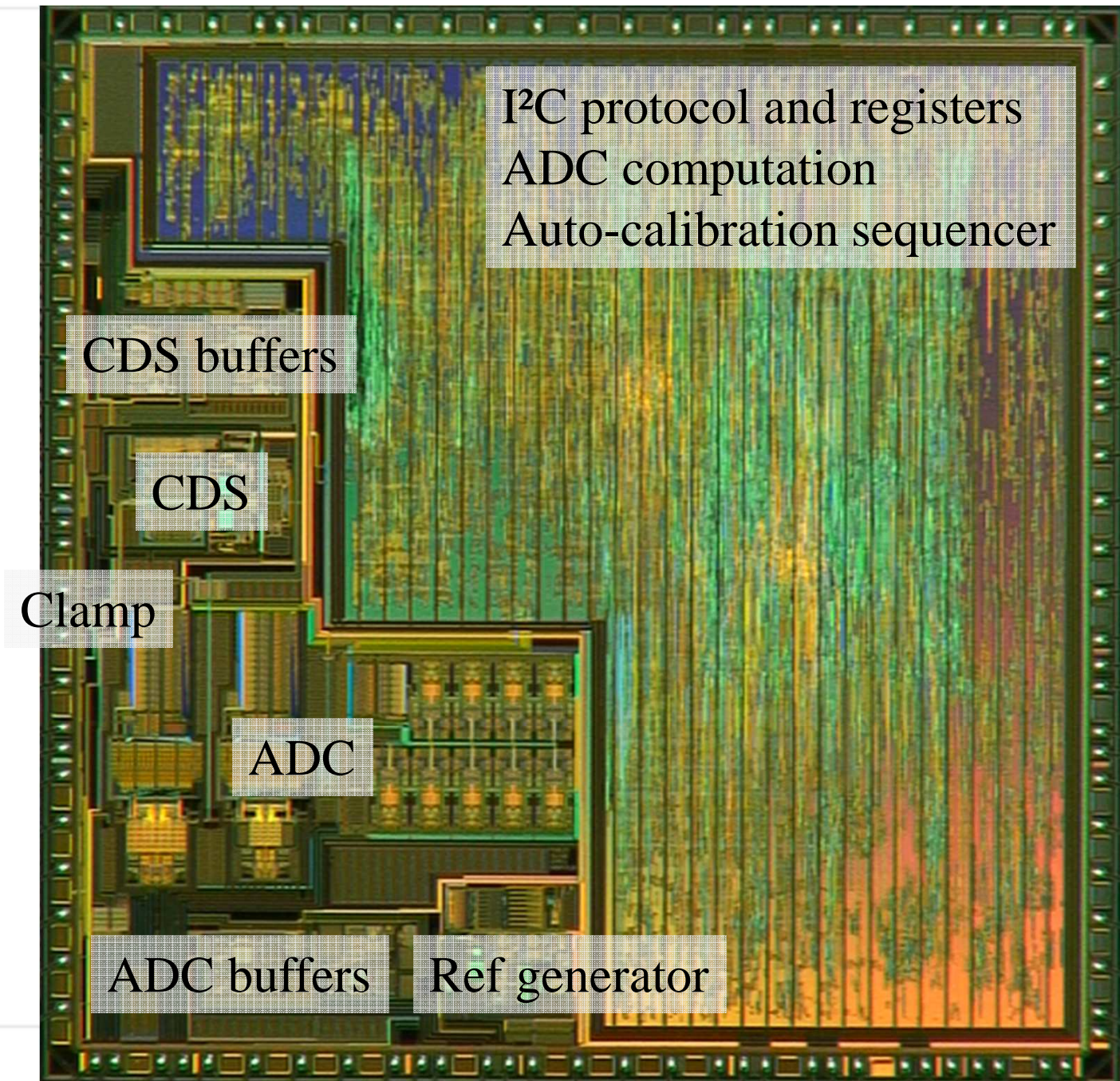


VASP1 - 81mm² - 108 IOs

Hardening : Analog 100% - digital 100%

ADC only consumption : 55 mA typ

Layout

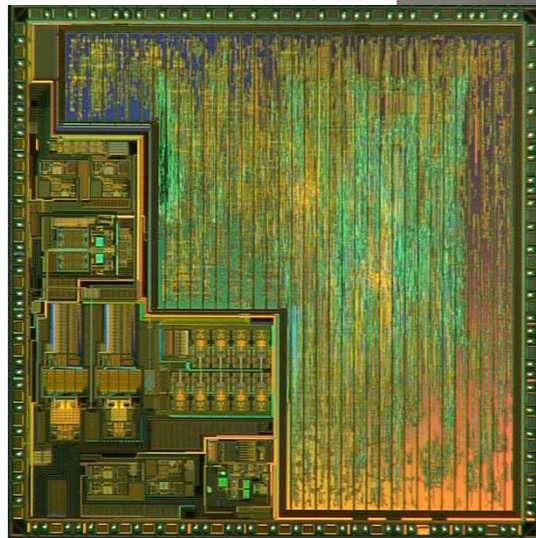
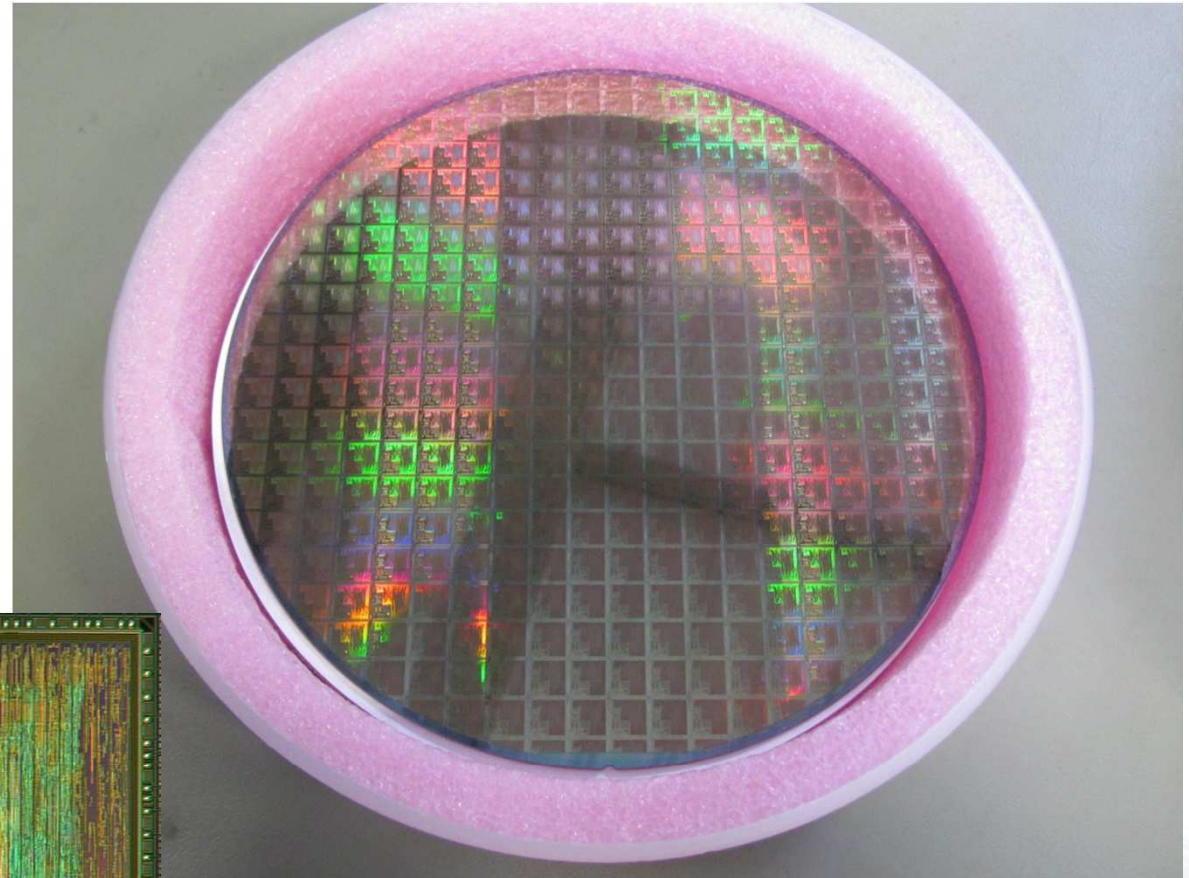


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Wafer and Die

XFAB 0.35 μm CMOS

- 8" wafers
- 250 VASP1 / wafer
- 3 months manufacturing
- Delivery on time
- PCM available



Package part

➤ HCM assembly

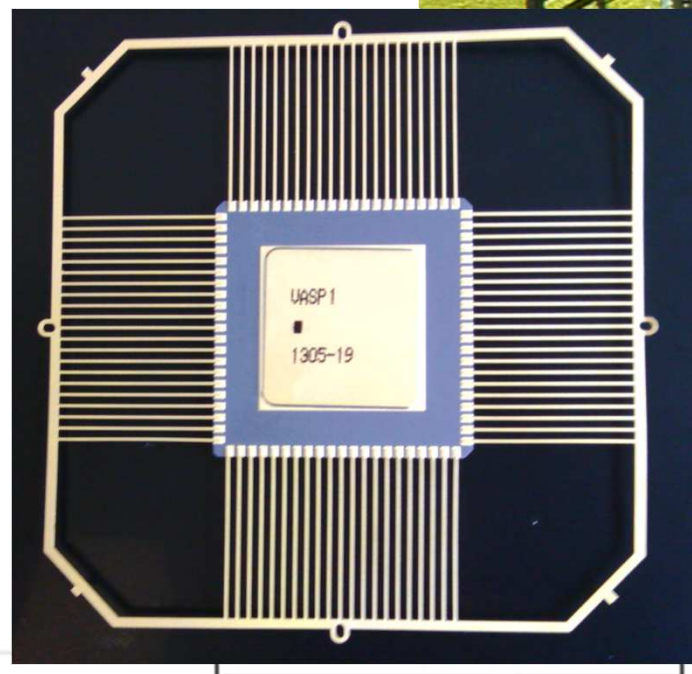
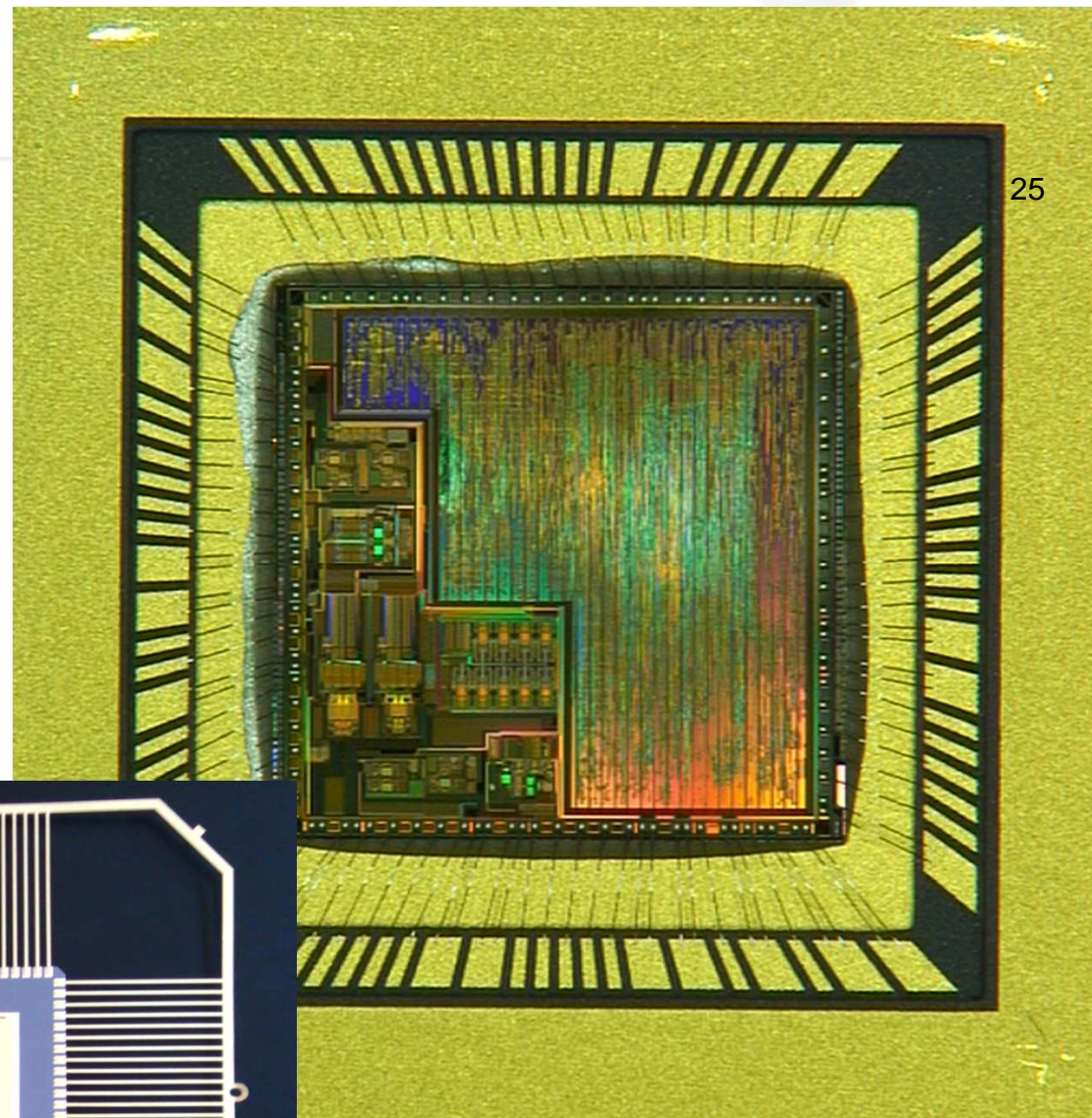
➤ CQFP84

➤ SERMA technology

➤ Wafer sort

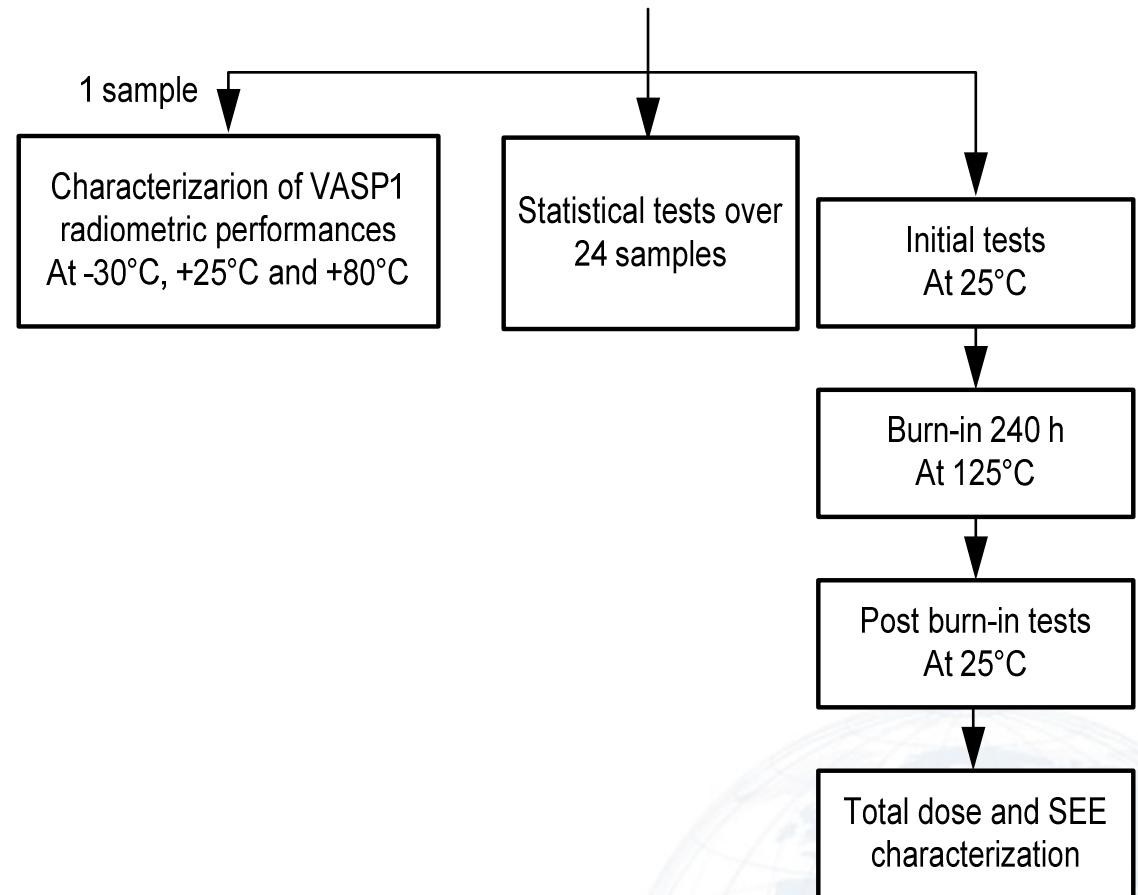
➤ Packaged electrical test

➤ ESCC 9000 test



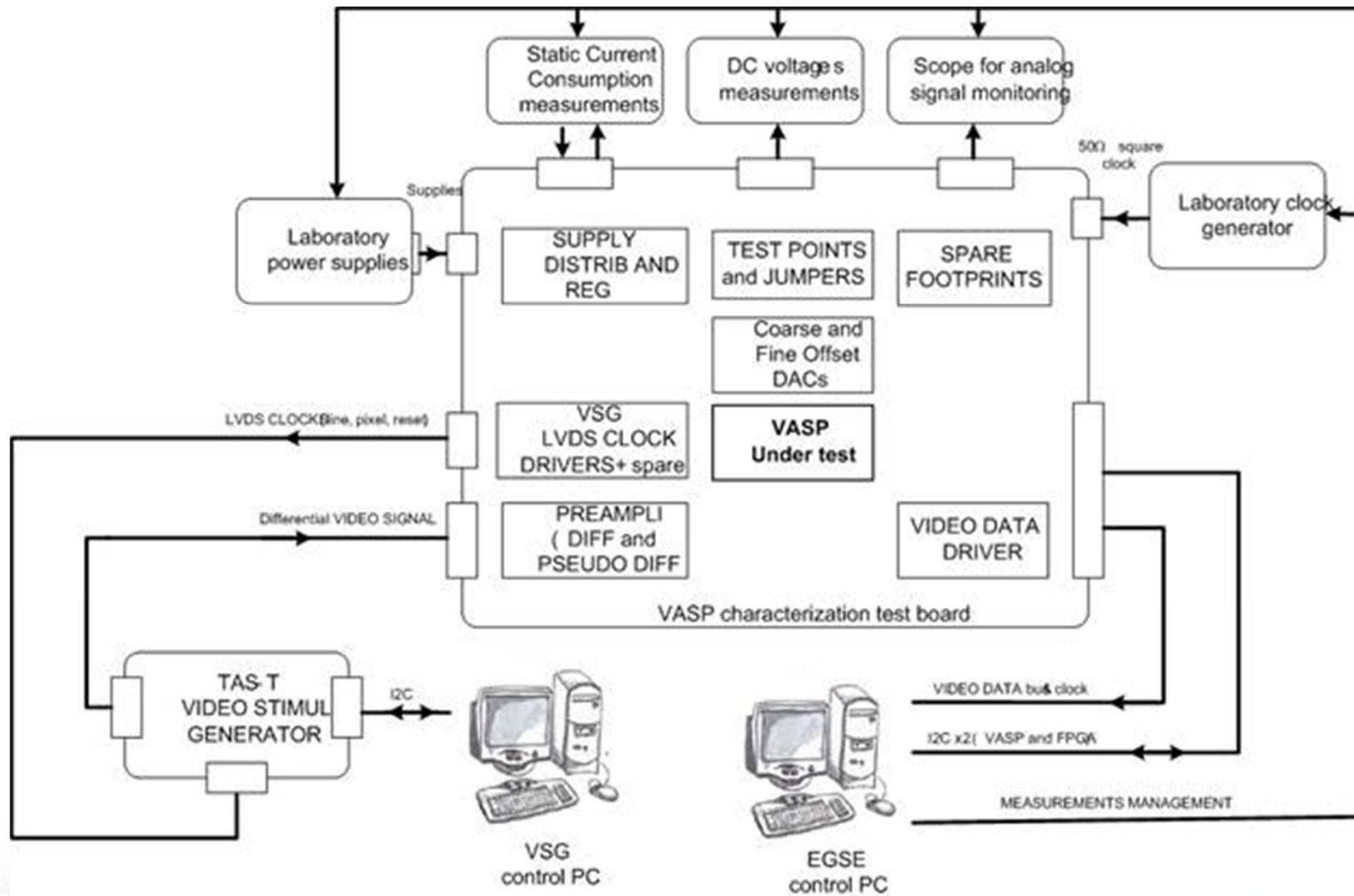
➤ The test plan consists in :

- The full characterisation of one sample
- Statistical tests on ~25 samples
- Radiation tests (TID and SEE).



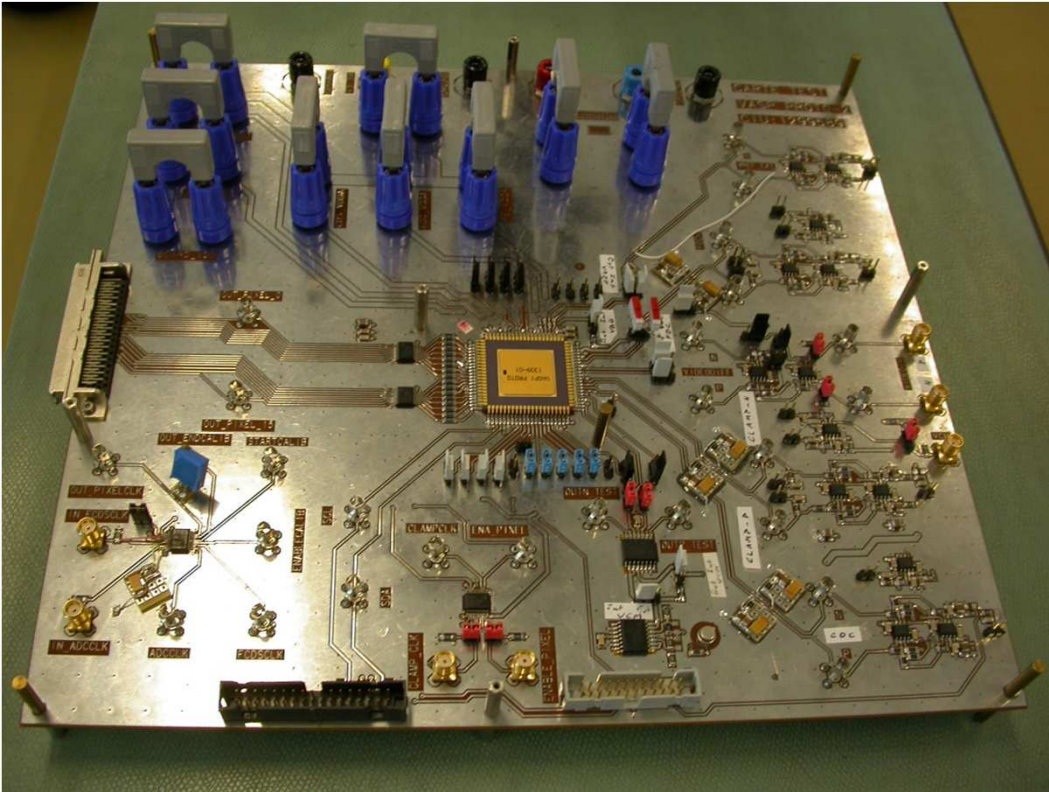
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VASP1 EGSE

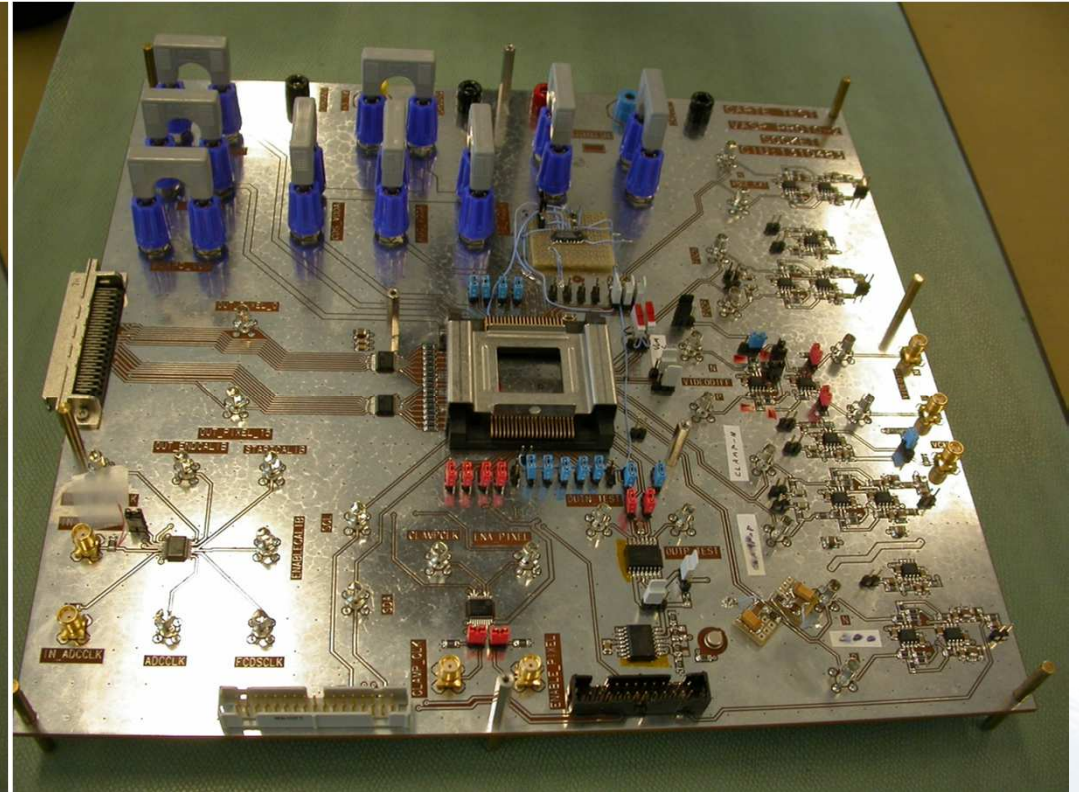


VASP1 EGSE / Test Boards

VASP1 Characterization Test Board



VASP1 Statistical Test Board



Power consumption

Power consumption (3,3V / at 4 MHz)

Idd VASP1	Measure (mA)
CDS+ADC Mode Voltage references activated	103
CDS+ADC Mode Voltage references deactivated	94
ADC Only Mode Voltage references activated	55
ADC Only Mode Voltage references deactivated	48

@ 100 kHz, 12 mA reduction

➤ Digital

- All functionalities have been checked and are as expected
- I/O parameters
 - Characteristics are as expected
- I²C link has been validated up to 1 MHz
- Digital scan ok

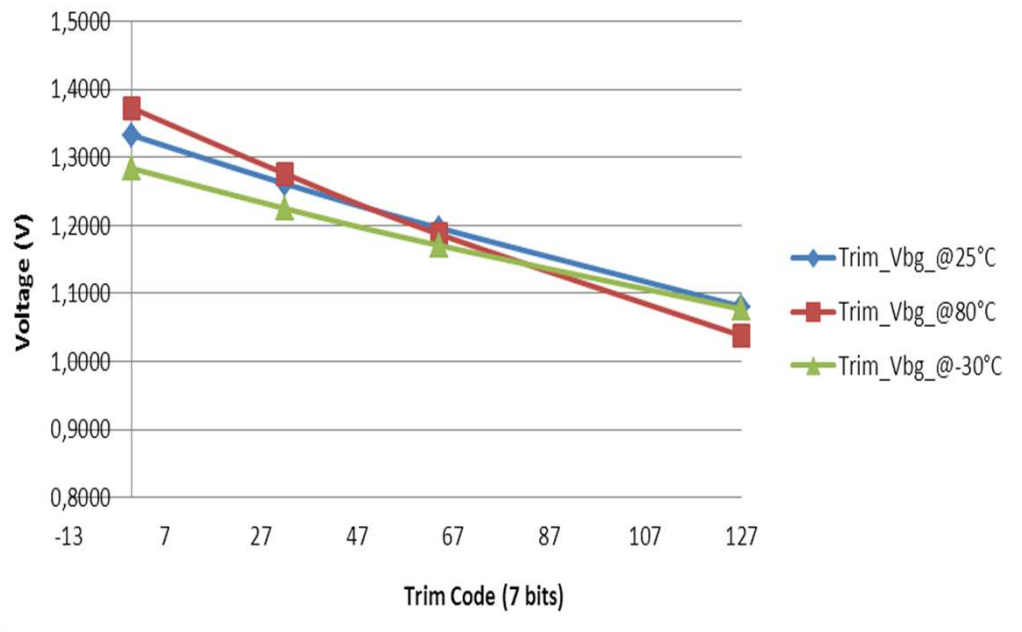
➤ Clamp

- Functionality proven
- Typ. ON resistance 70 Ohms

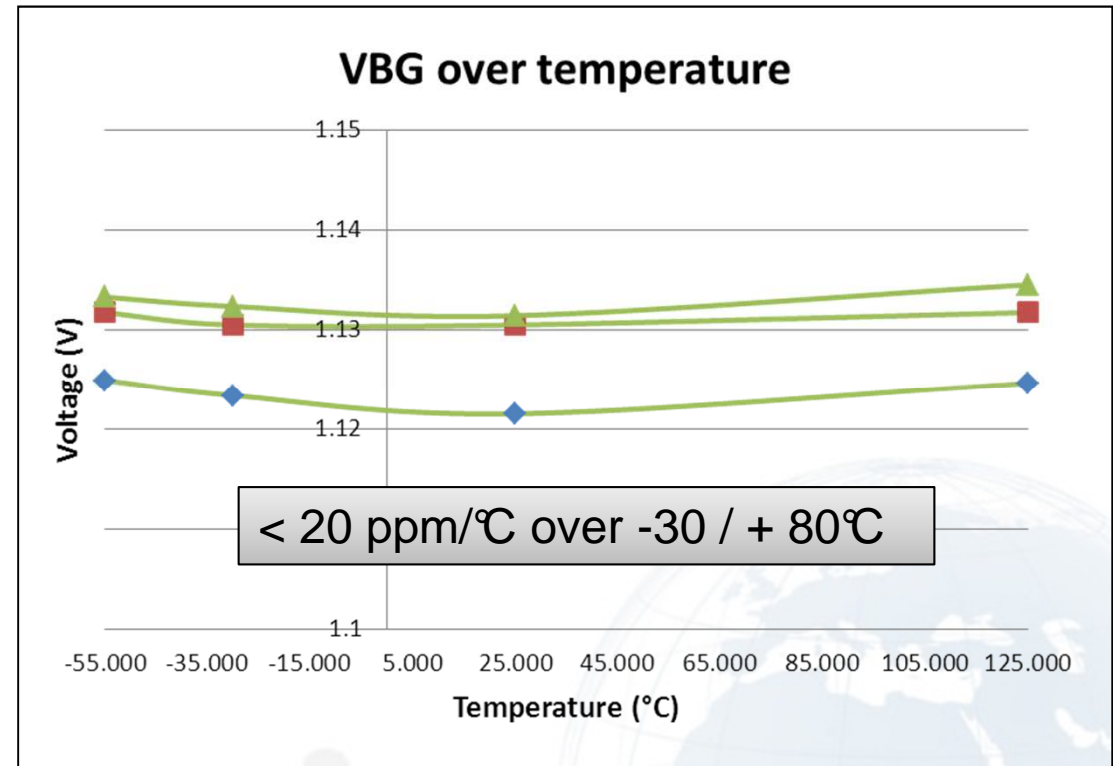
Reference voltages

- Temperature stability of VBG (bandgap) is programmable with a 7 bit word through I²C.

Trim Vbg voltage



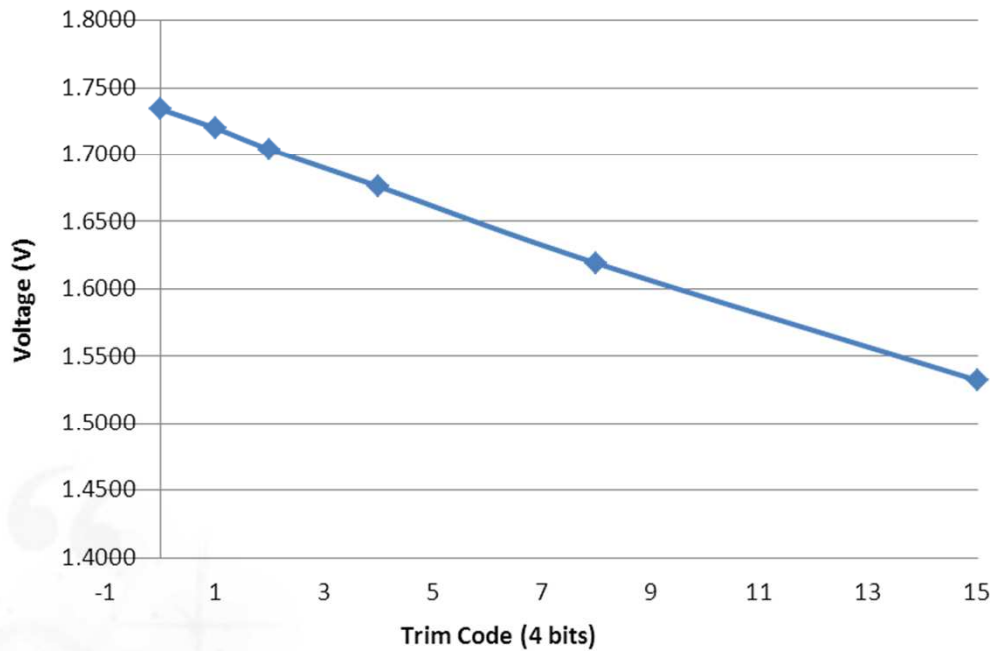
VBG over temperature



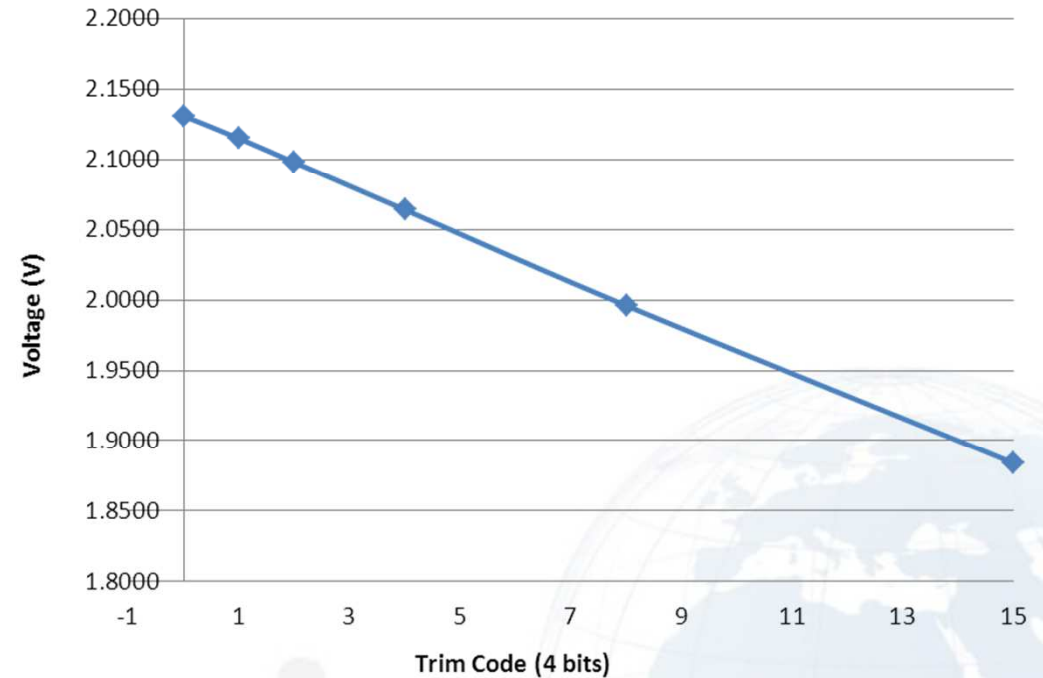
Reference voltages

- Reference voltages values (V_{cm} and V_{ref}) are programmable with 7 bit words through I²C.

Trim V_{cm} voltage



Trim ΔV_{ref} voltage



External reference

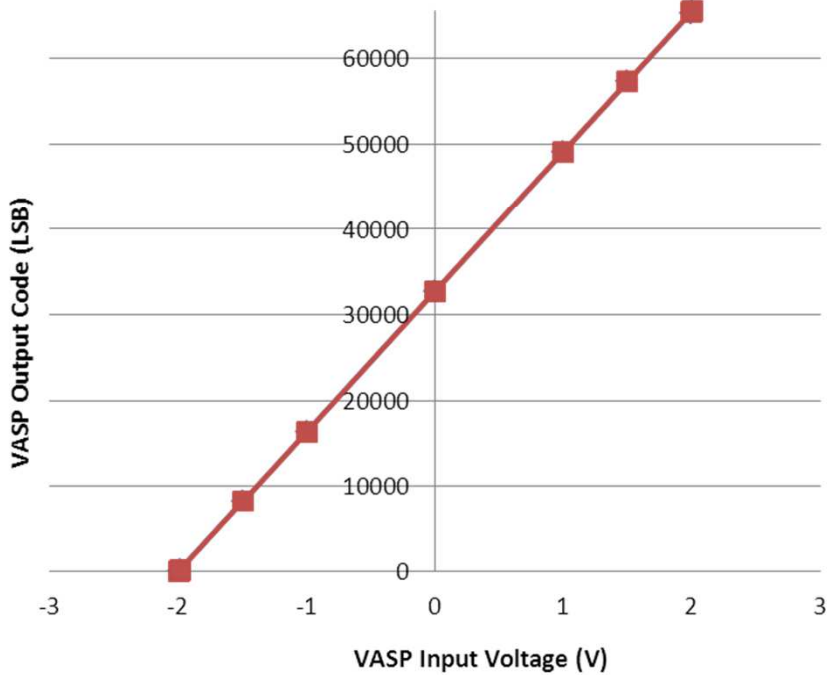
- Functionality proven

Internal buffers

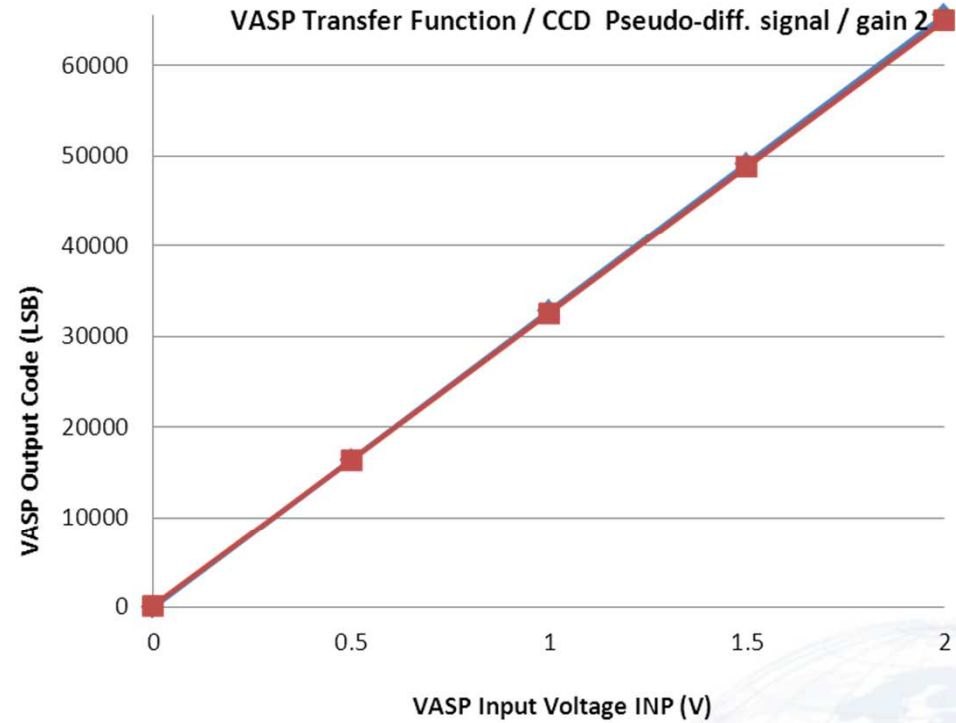
- ADC and CDS reference voltage buffers validated
- FOC and COC voltage buffers validated

➤ Digital conversion transfer function

VASP Transfer Function / CMOS diff. signal / ADC_only Mode



VASP Transfer Function / CCD Pseudo-diff. signal / gain 2



◆ Ideal Transfer Fct
■ Transfer_Fct_@25°C

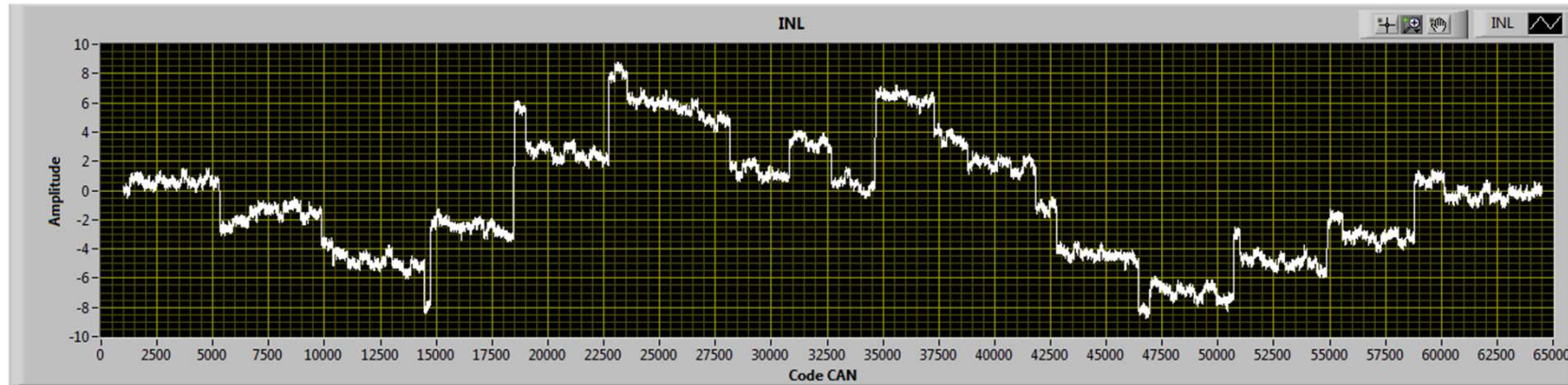
➤ Measured Input Referred Noise (LSB rms), at 4MHz

Temp	-30°C	25°C	80°C
CCD mode	2.3	1.9	1.9
CMOS mode	1.6	1.9	1.4
ADC only mode	0.7	0.8	0.85

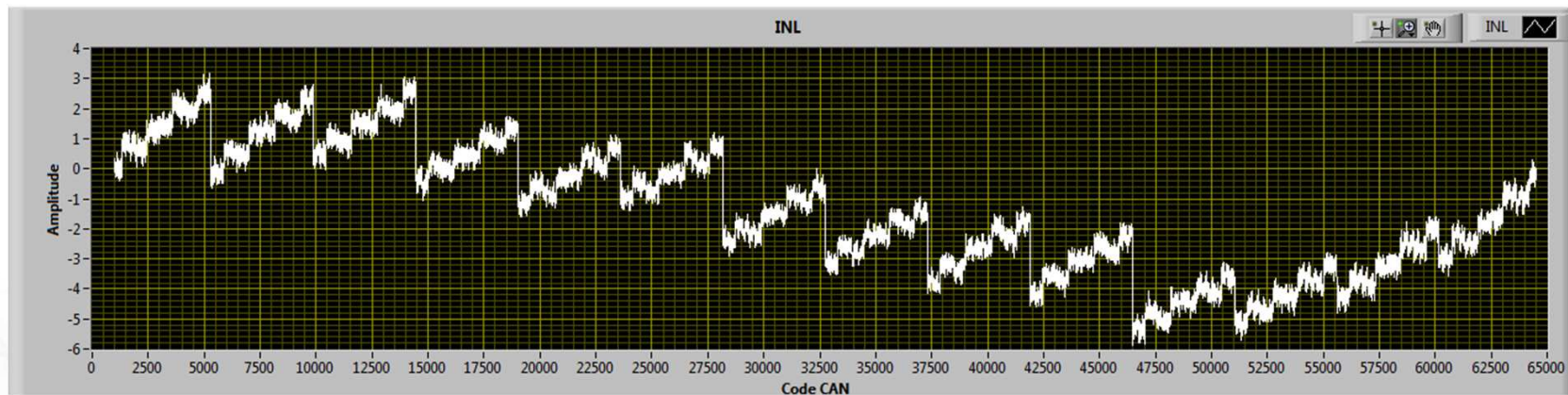
VASP1 characterisation results (4/5)

➤ Linearity calibration, at 4MHz

➤ INL before calib (17.6 LSBpp)

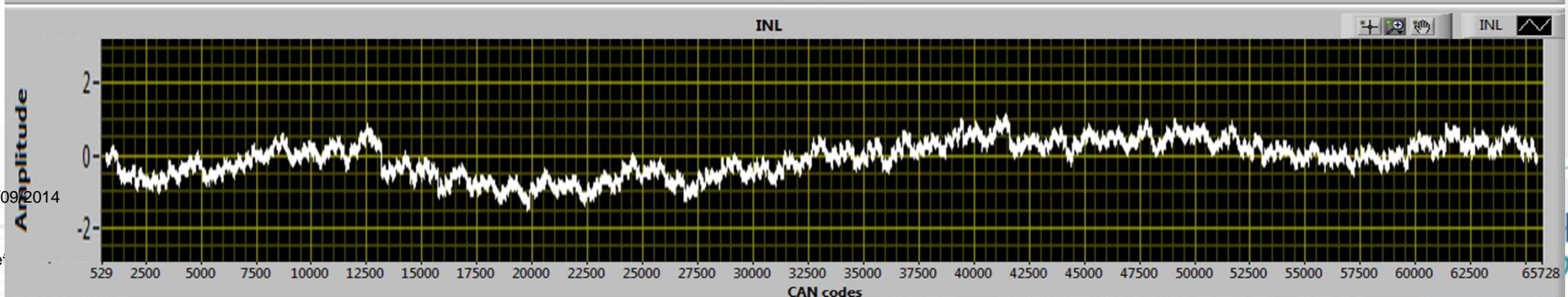
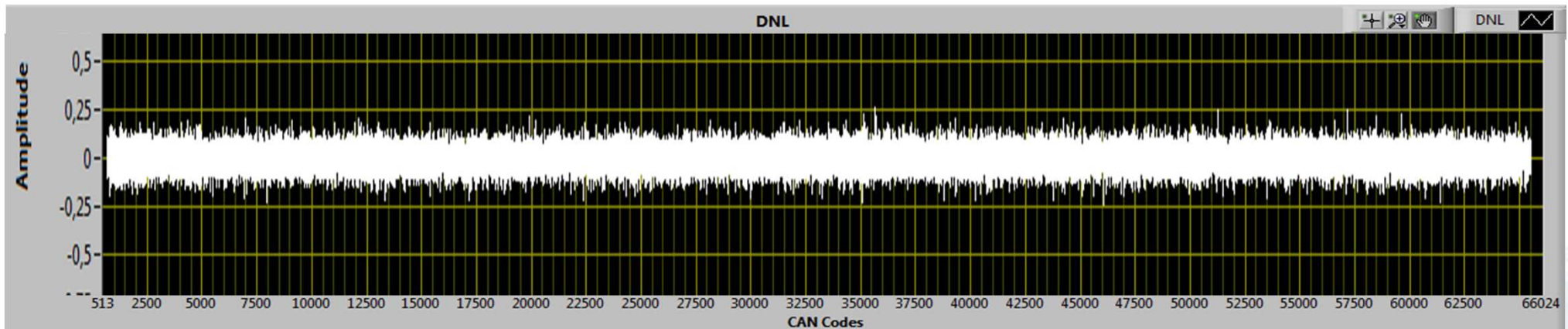


➤ INL after calib (9 LSBpp)



ADC Linearity, at 4MHz

- ADC linearity has been measured on MTG bench with very good compensation of bench defaults.
- Performance is measured after internal calibration
 - **Peak DNL is +0.26 Lsb and -0.26 Lsb** (< 0,5 Lsb expected)
 - **Peak to peak INL is 2.7 Lsb** (4 Lsb expected performance).



➤ **ADC Gain**

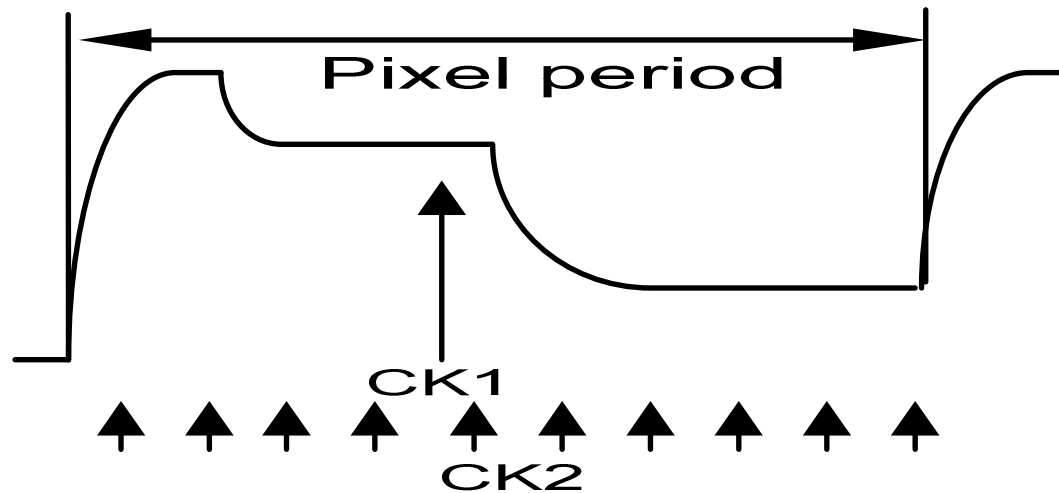
- By principle, gain is exactly $2 \times (V_{refp} - V_{refn})$.
- Gain stability is $< 10 \text{ ppm/}^\circ\text{C}$ after tuning (over $30 \text{ }^\circ\text{C}$ range)

➤ **Offset** (ADC only mode)

- Offset $< 50 \text{ Lsb}$
- Offset stability : $< 5 \text{ Lsb}$ from -30°C to $+80^\circ\text{C}$ (ADC only mode)

Multi-sampling

- Allow noise reduction on low frequency pixel
- Functionality proven



Offset correction inputs:

- Coarse offset correction (when CDS is used)
 - COCP-COCN injects a regular offset around 2V
 - The offset correction gain is one => ~ 16 LSB/mV
 - Functionality proven
- Fine offset correction
 - FOCP-FOCN injects a regular offset around 0V (FOCP = FOCN = 1.65V)
 - The offset correction gain is one quarter => ~ 4 LSB/mV
 - Functionality proven

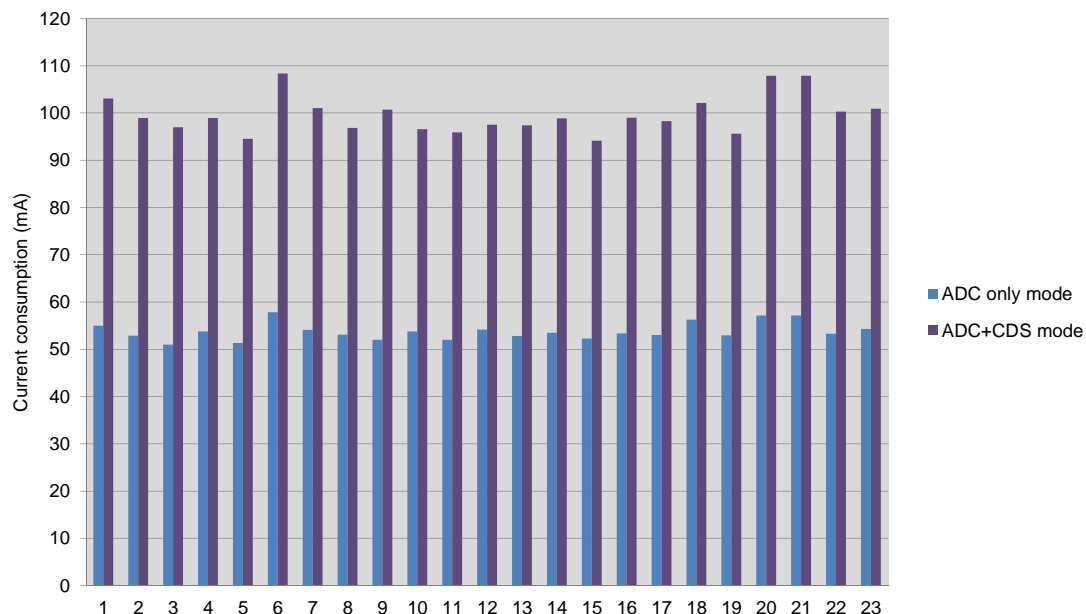
VASP1 intrinsic offset

- < 50 LSB
- < 5 LSB variation over temperature range

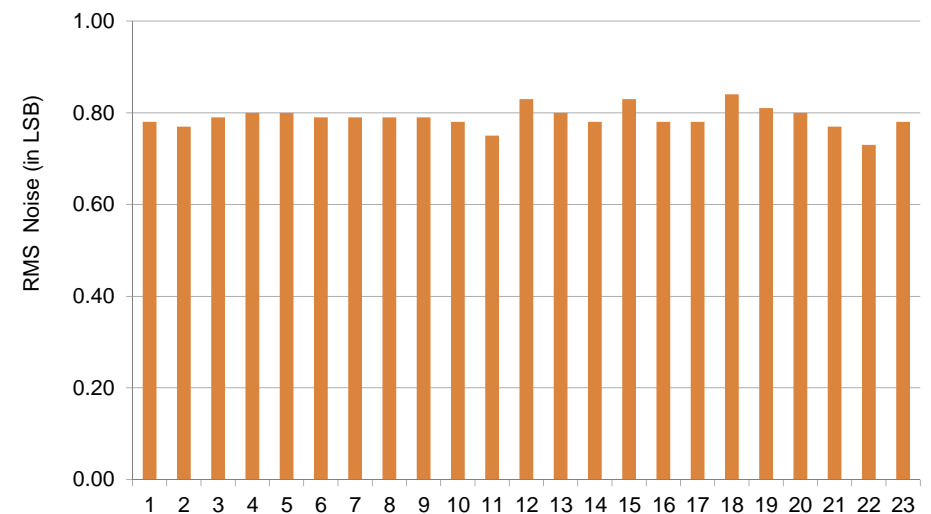
VASP1 ASIC statistical tests are successful

- 23 of the 24 samples tested give OK result. (yield > 95 %)
 - The only sample NOK has manufacturing default. It is rejected only at this step because it was not tested by ASIC foundry.
- Test results are very homogenous on all the samples tested are OK.

Power consumption of 23 VASP1 proto parts



Typical noise on 23 ASIC parts (CMOS signal / ADC Only Mode)



- The VASP1 validation tests confirmed
 - **functions and performances are compliant** to the ones described by its preliminary datasheet in the full frequency range and in the nominal temperature range.
 - Large margins are demonstrated by additional testing @ -30°C and up to 5 MHz.
- Every good sample behaves the same way

VASP1 electrical validation is successful

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✈ Board, program and measurement made by TRAD – Toulouse

✈ Dose

- ✈ ^{60}Co source
- ✈ Steps : 0, 9, 23, 33, 43, 57, 72, 101 krad(Si)
- ✈ ESCC 22900 Low dose rate : 210 rad(Si)/hour .

✈ 3 biasings

- ✈ ON with clock (4 parts)
- ✈ ON without clock (3 parts)
- ✈ OFF (3 parts)

✈ Annealing

- ✈ 25°C for 24h
- ✈ 100°C for 168h

- **Very few parameters drifted, within specifications**
 - Leakage current in the input digital IOs
 - Input current for pin having pull-up function activated
- **All others parameters are extremely stable**
 - Bandgap reference voltage (and associated voltages)
 - Chain offset
 - Consumption
 - ADC performances (Linearity, noise, offset)
- **Full recovery after annealing**

VASP1 is fully functional and specification compliant up to 100 krad(Si)

- **Board and program made by TRAD – Toulouse**
- **Measurement made by TRAD – UCL Louvain**

- **SEL** test monitoring of supplies

- **SET** test monitoring of :
 - Analog references
 - Erroneous digital conversion

- **SEU** testing monitoring of register map program and read back

- **SEFI** monitoring of abnormal behavior during test

SEL

- **No SEL** @ LET=67.7 MeV.cm²/mg up to fluence of 1E7 ions/cm²

SEU

- Very low susceptibility of register : SEU LET_{th} = 20.4 MeV.cm²/mg with ssat = 1E-06 cm²
- Reset register sensitivity : LET_{th}> 40.4 MeV.cm²/mg with ssat = 1E-07 cm²
- **The probability of SEU is extremely low**

SET :

- **No SET observed on references** @ LET=67.7 MeV.cm²/mg
- **ADC output code error** (criterion > 64 Lsb16) : LET_{th}=10.2 MeV.cm²/mg with ssat = 6E-05 cm²

SEFI

- **No SEFI detected in any condition**

Conclusion on VASP1 design

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➤ Based on the very good VASP0, we managed to complete the design of a Video Acquisition Signal Processor.

➤ Many thanks to the core team

Philippe Ayzac, Anthony Berne, Jorge Guilherme, Claude Neveu, Jean-Marie Saveres, Franck Mariannie, Denis Lagarde, Marc Medard, Michel Carquet, Charly Bonnet, Sylvain Claireux, Michael Laine



➤ Many thanks to the whole team

Jean-Marie Garigue, Sophie Di Santo, Emmanuel Liegeon, David Le Du, Laurent Venturini, Laurent Carre, Raoul Velazco, Kholdoun Torki
and many other contributors...

➤ Many thanks to Wahida Gasti for her exigency and trust despite all challenges

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➤ VASP1 datasheet is available :

➤ Title :

VASP1 DATASHEET

➤ Ref : 100535705O

➤ issue 3.2

➤ date 2014-07-04

➤ It provides full functional and performance information.

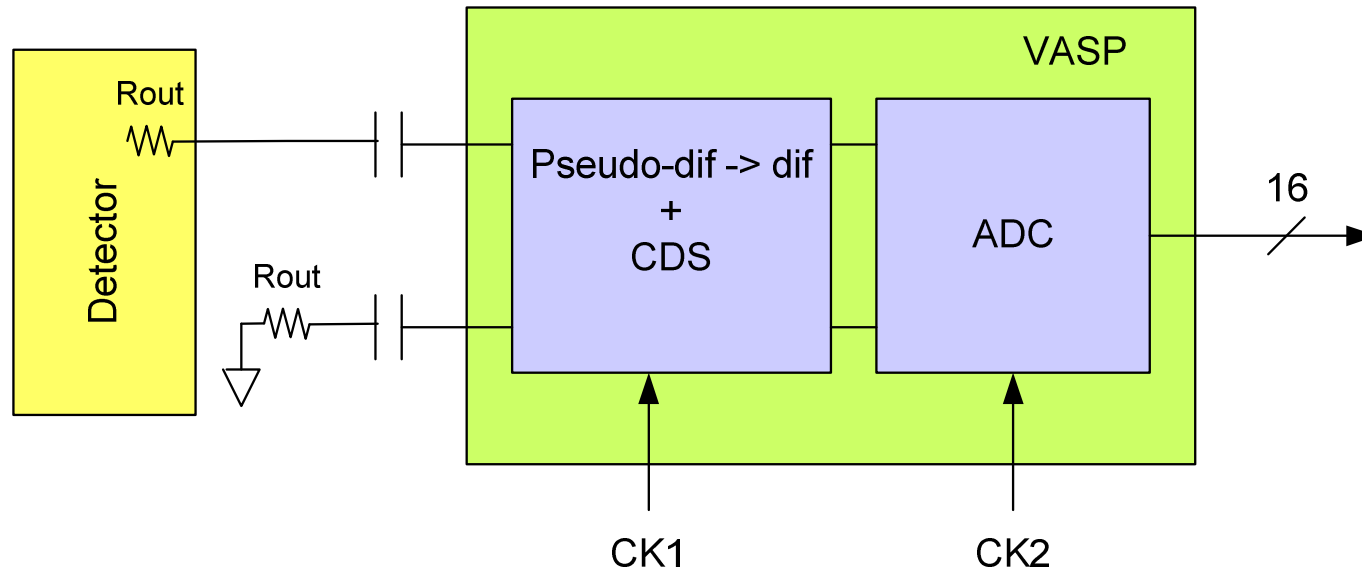
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- VASP1 is designed to be used with CCD and CMOS detectors

- VASP is compatible of numerous video processing chain architectures, which depend on :
 - Type of detector, CCD or CMOS
 - Pixel frequency
 - Detector proximity, power and size constraints

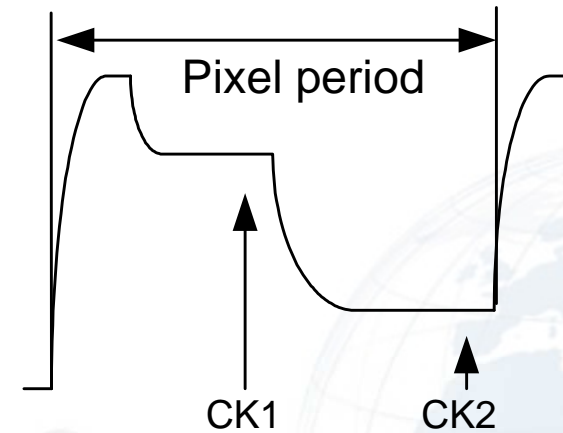
- Most usual architectures are shown in the following slides.

CCD – Low pixel frequency – Detector proximity

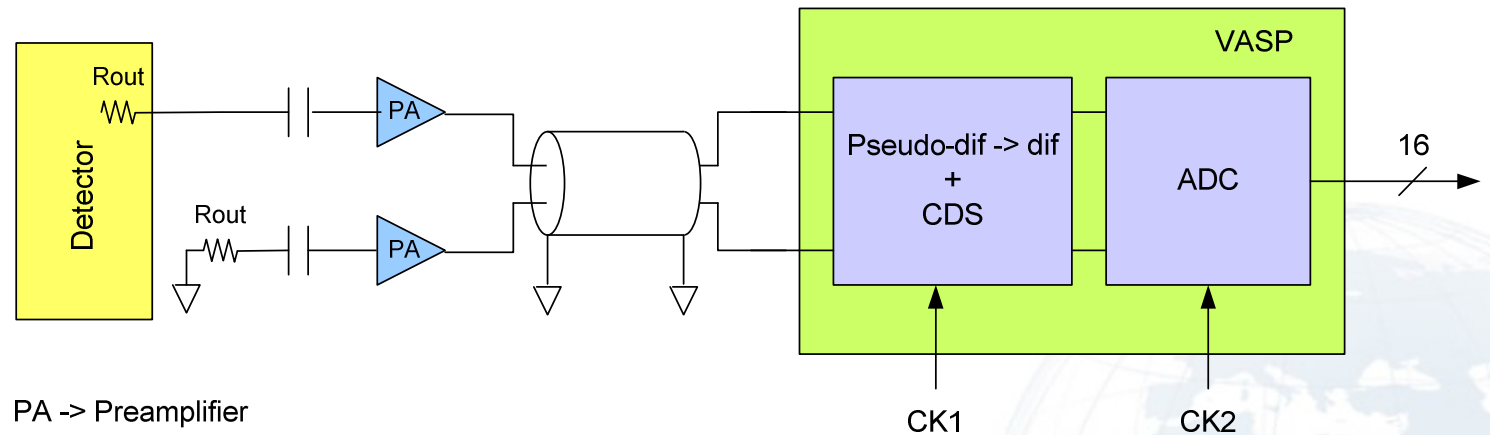
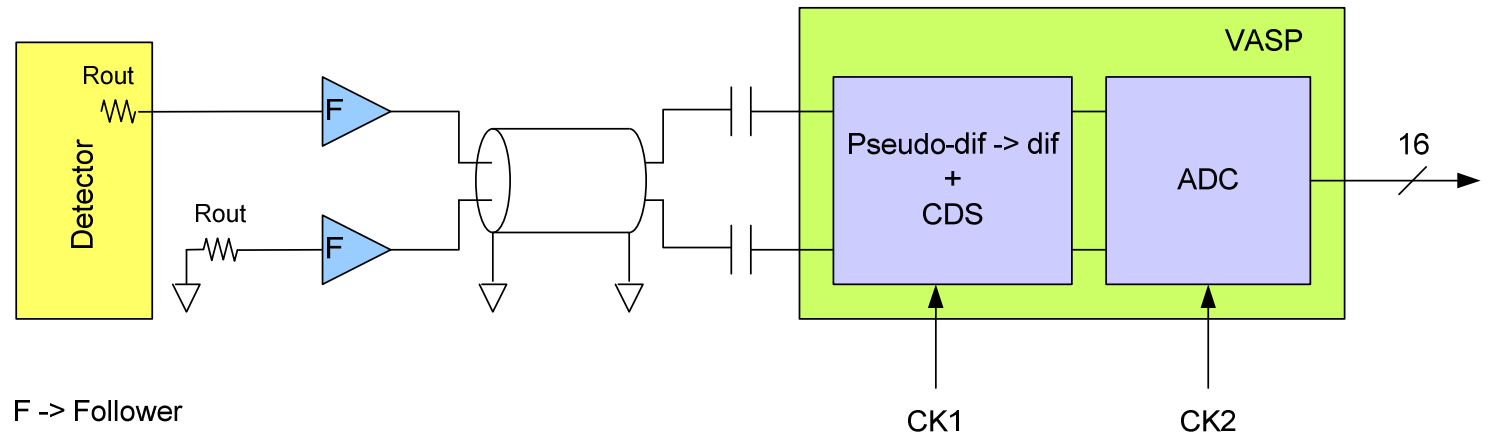
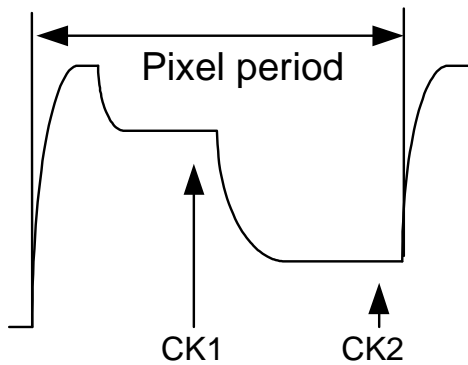


Example of potential applications :

- Sensors



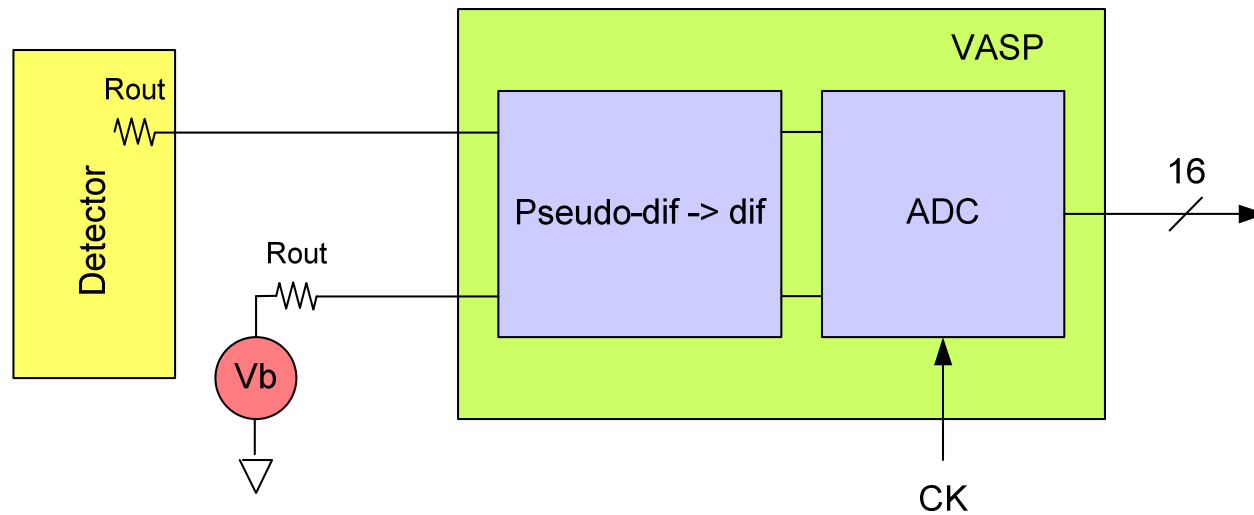
CCD – High pixel frequency – Remote video processing



Example of potential applications :

- Earth observation
- Scientific mission

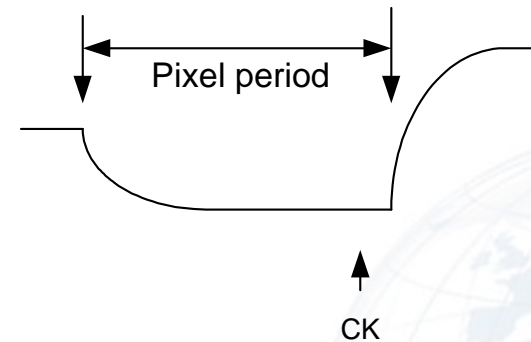
CMOS – Low pixel frequency – Detector proximity



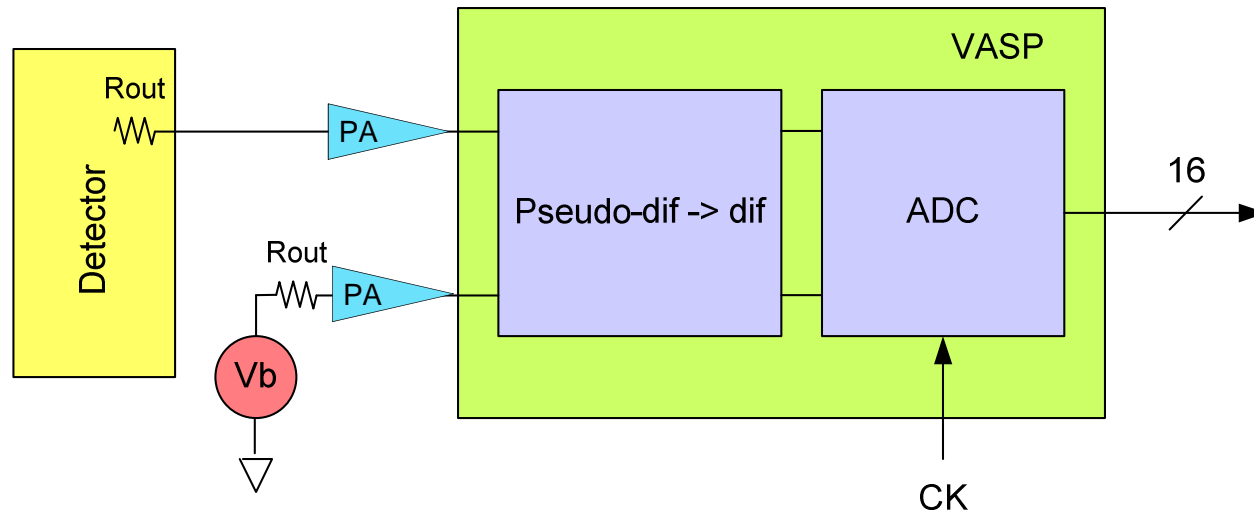
Vb -> Black pixel pedestal

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- Sensors



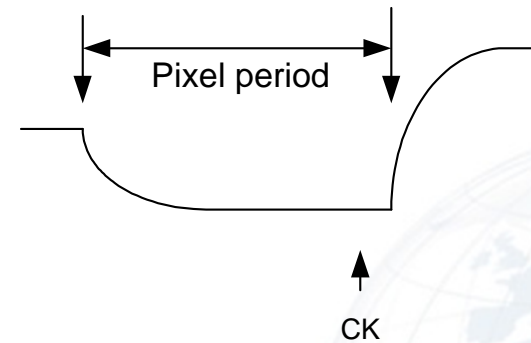
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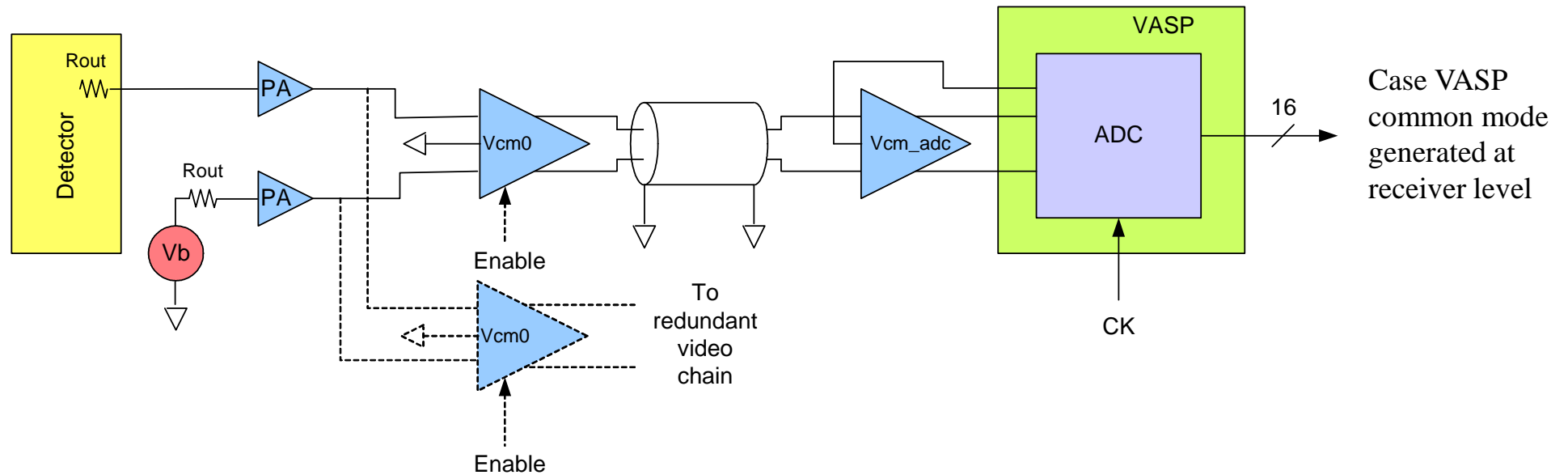
Vb -> Black pixel pedestal

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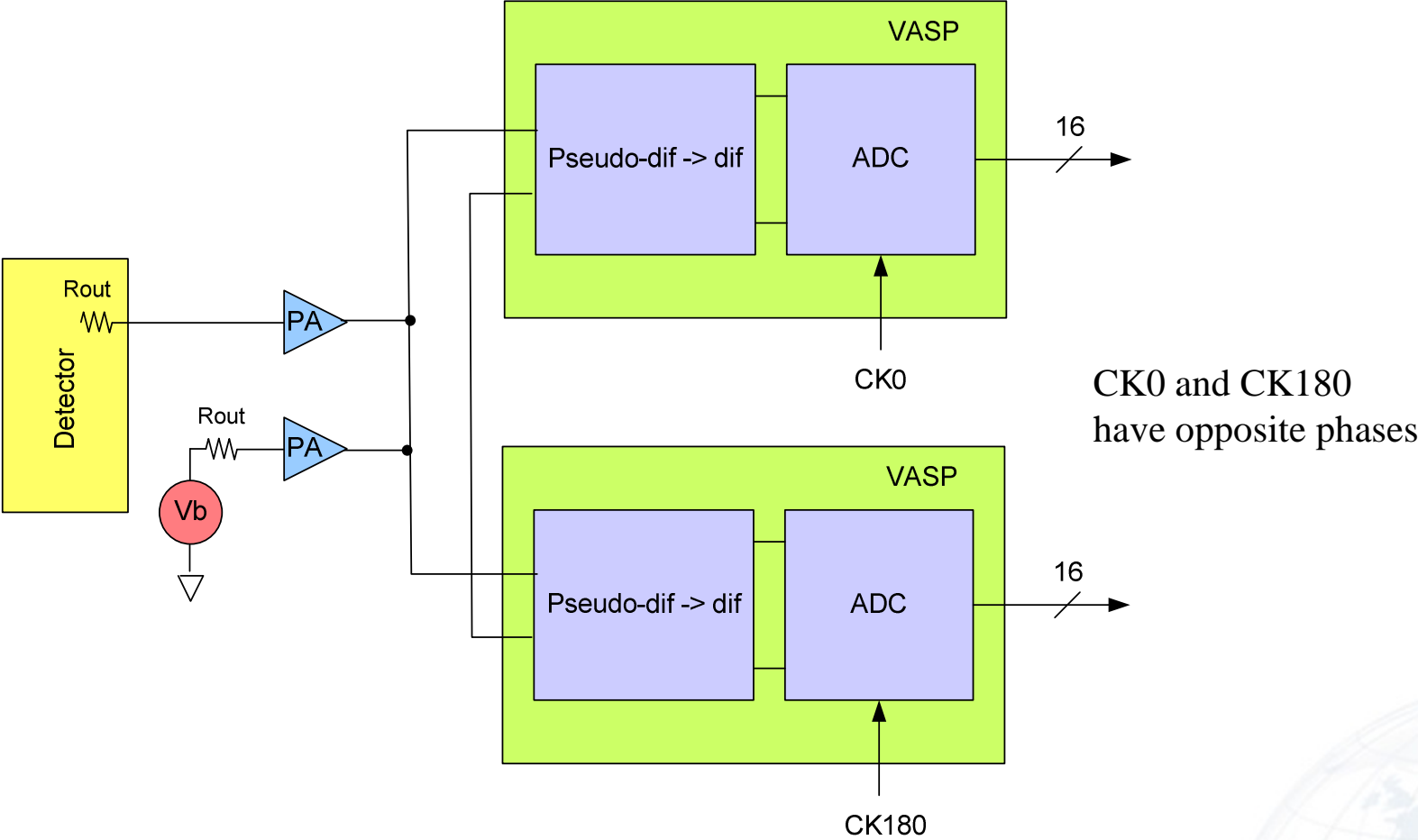
CMOS with redundancy on video processing



Example of potential applications :

- SEN2/MSI
- MTG/FCI
- Most of high performance, high reliability IR imagers

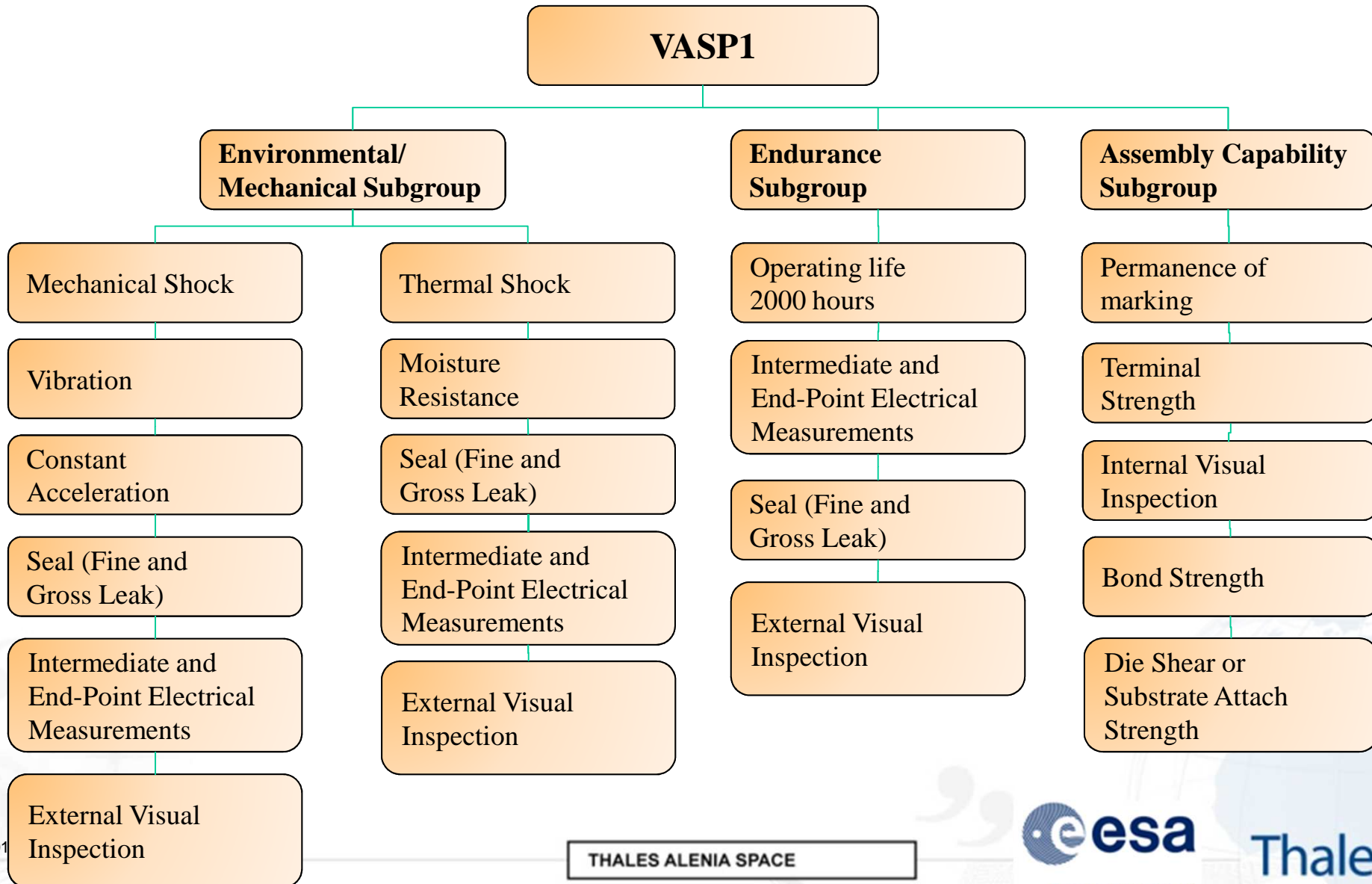
2 VASP1 for increasing sampling frequency up to 8 MHz



- Introduction on HIVAC contract
 - HIVAC Activity
 - VASP0 ASIC development
- VASP1 ASIC development
 - Specification
 - Design
 - Manufacturing
 - Electrical test
 - Radiation test
- VASP1 datasheet
- VASP1 application
- **FM production**
- Conclusion

FM qualification

Consistent with ESCC Generic Specification No. 9000 (chart F4)



Foundry

- XFAB
- ISO 9001:2000/2008
- Automotive referential : ISO TS 16949:2002/2009
- Lot PCM
- Customer alert via automated email

Back-end activities

ESCC Generic Specification No. 9000

- Partners selected to cover all the activities :
 - Packaging : HCM-Systrel
 - FM production and qualification : SERMA Technologies

➤ Introduction on HIVAC contract

- HIVAC Activity
- VASP0 ASIC development

➤ VASP1 ASIC development

- Specification
- Design
- Manufacturing
- Electrical test
- Radiation test

➤ VASP1 datasheet

➤ VASP1 application

➤ FM production

➤ **Conclusion**

Conclusion

- **Objective of a highly integrated video analog front-end is 100% validated**
 - CDS, clamp and buffers
 - ADC and buffers
 - Internal references
- **Outstanding performances of 16-bit ADC with minimum power consumption**
- **TAS radiation hardening design rules** allow to stand a high level of hardness, for TID and SEE as well.
- **VASP1 Qualification has been performed in full compliance to ECSS-Q-ST-60**
- **FM production of this complex mixed ASIC** for space application is on-going.



VASP1 FM available in Q2 2015

Questions ?

Let's try VASP1 !

